

△ 0.15 C

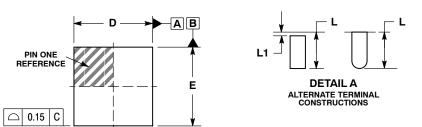
WQFN10 2.6x2.6, 0.5P CASE 510AJ-01 **ISSUE A**

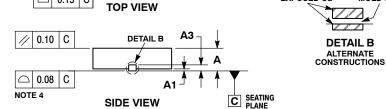
EXPOSED Cu

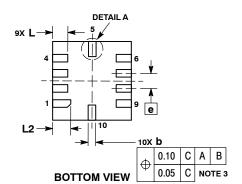
MOLD CMPD

DETAIL B

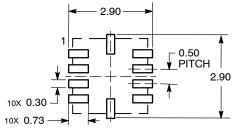
DATE 27 MAR 2009







SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
 0.15 AND 0.30mm FROM TERMINAL.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.70	0.80	
A1	0.00	0.05	
A3	0.20 REF		
b	0.20	0.30	
D	2.60	BSC	
E	2.60	BSC	
е	0.50 BSC		
L	0.45	0.55	
L1	0.00	0.15	
L2	0.55	0.65	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

= Assembly Location AA

Υ = Year

W = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98AON38696E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	WQFN10 2.6X2.6, 0.5P		PAGE 1 OF 1

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.